

XPS at Lehigh

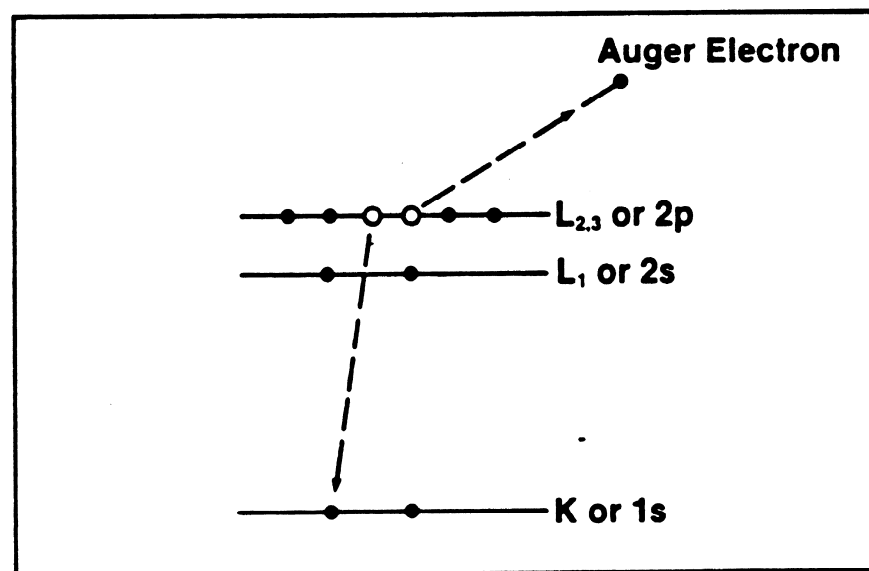
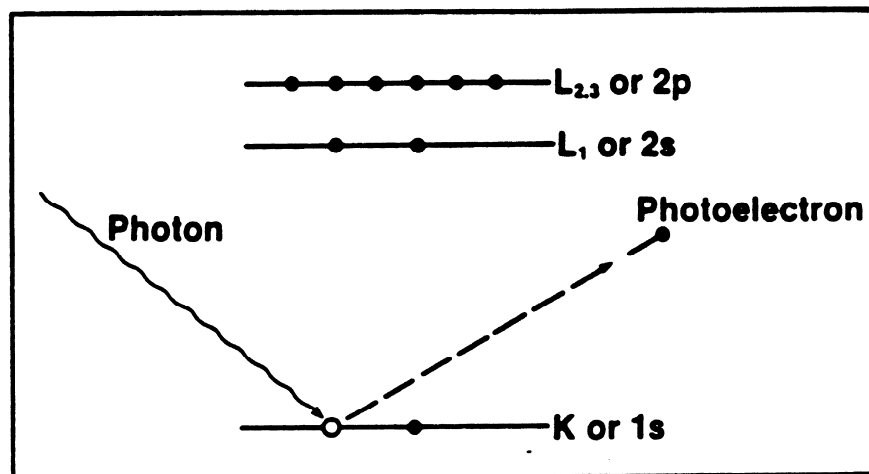
Dr. Alfred C. Miller

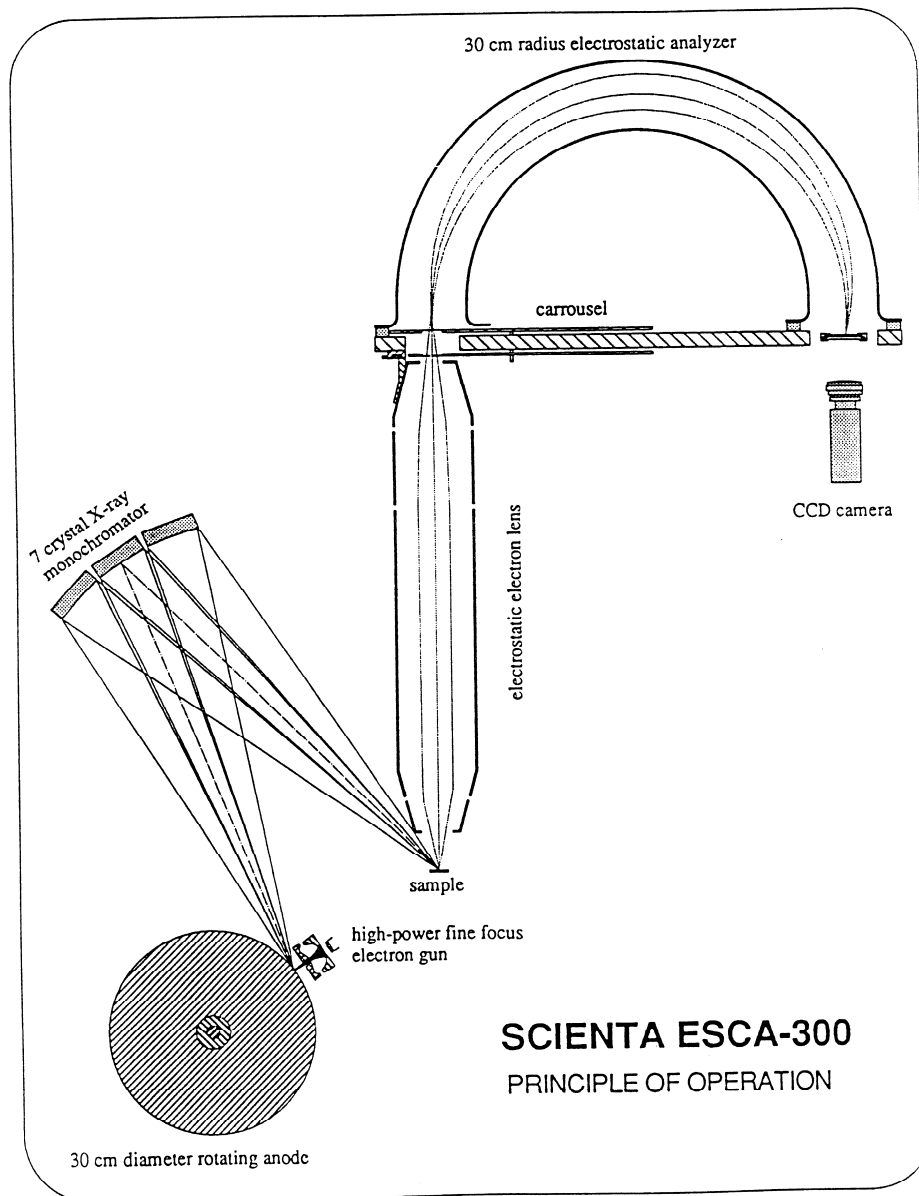
Overview

- Principles
- Instrumentation
- Examples
- Limitations
- Resources at Lehigh

Principles of XPS and AES

Maximum
escape depth for
electrons is less
than 10 nm





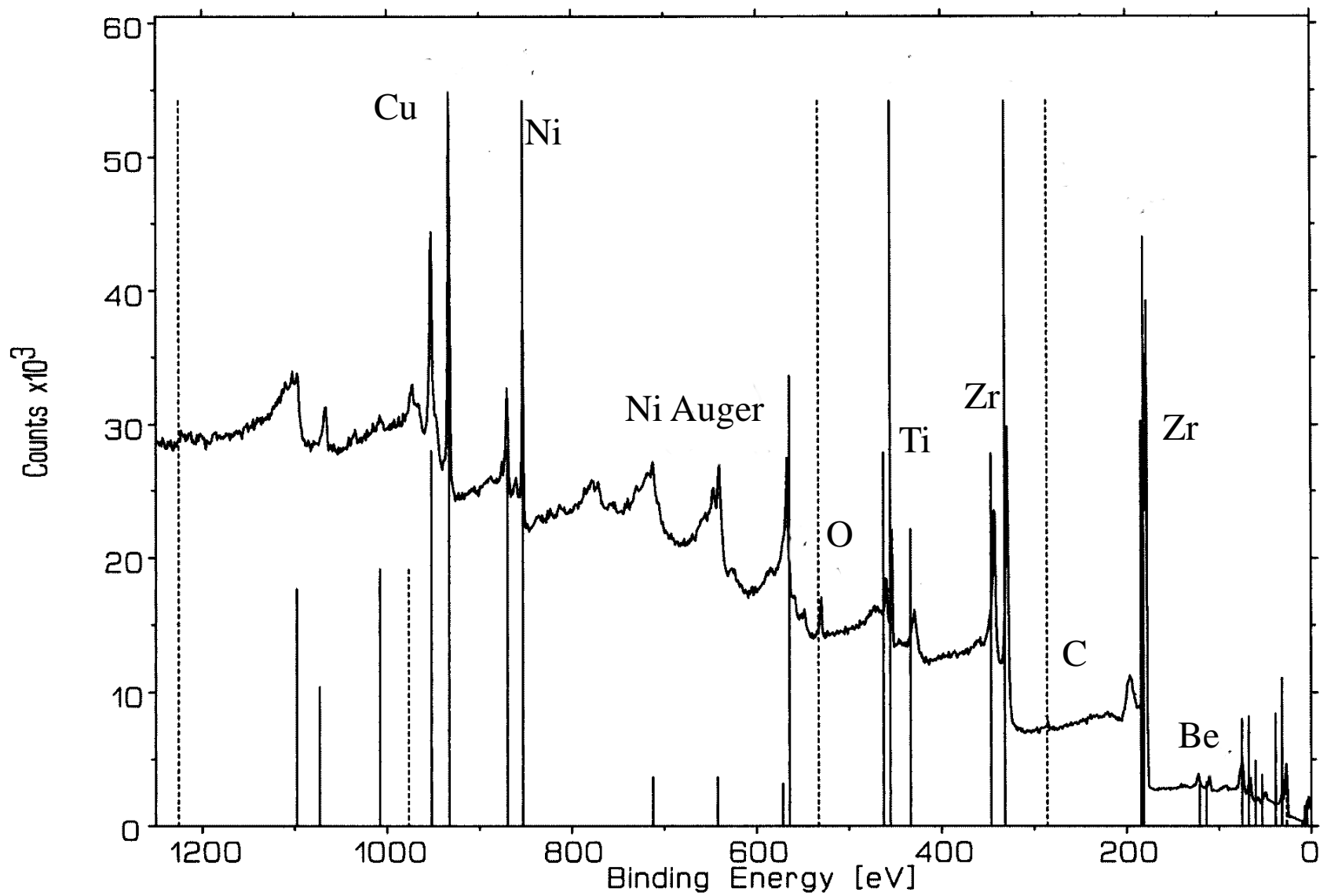
SCIENTA ESCA-300

PRINCIPLE OF OPERATION

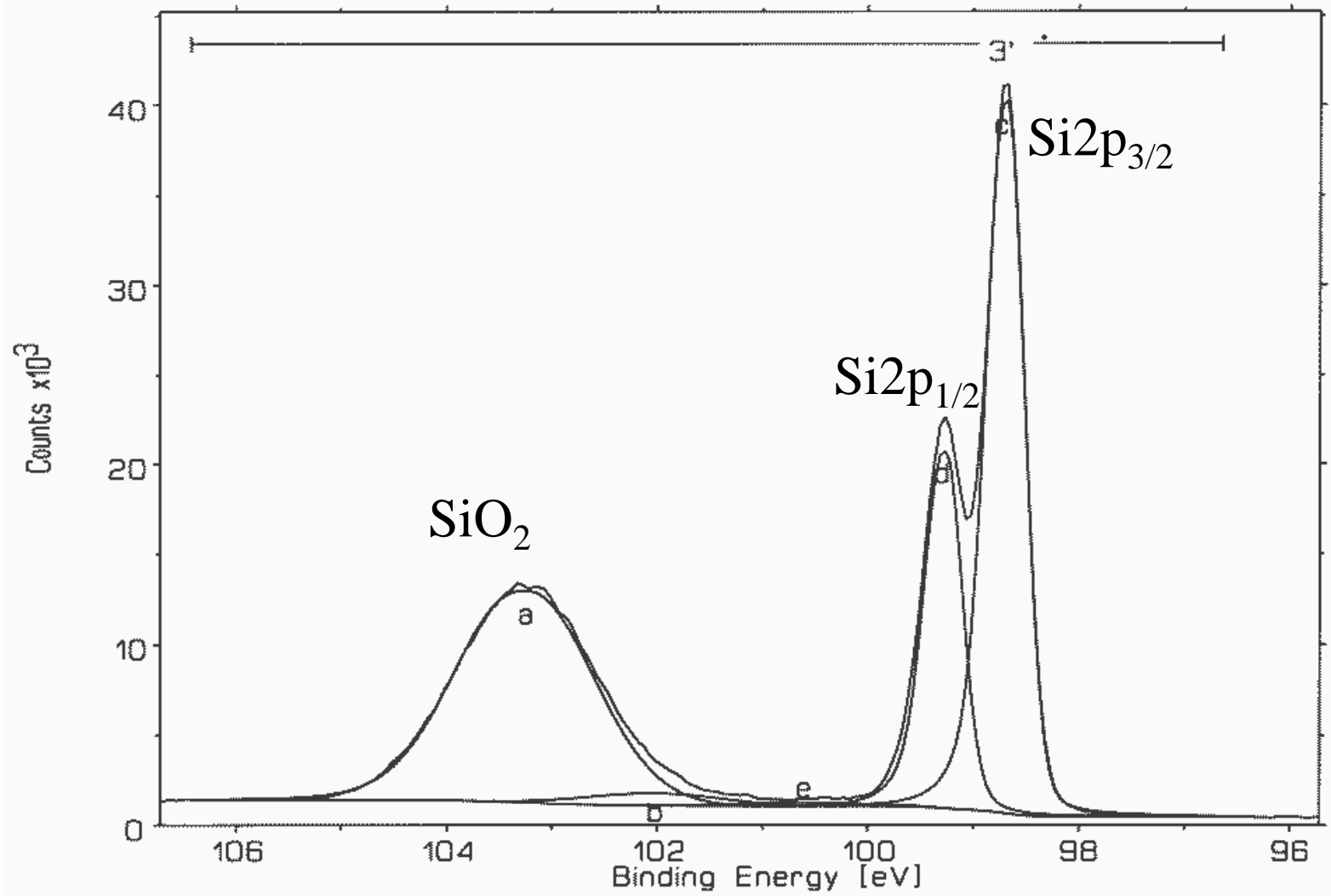
Spectral information

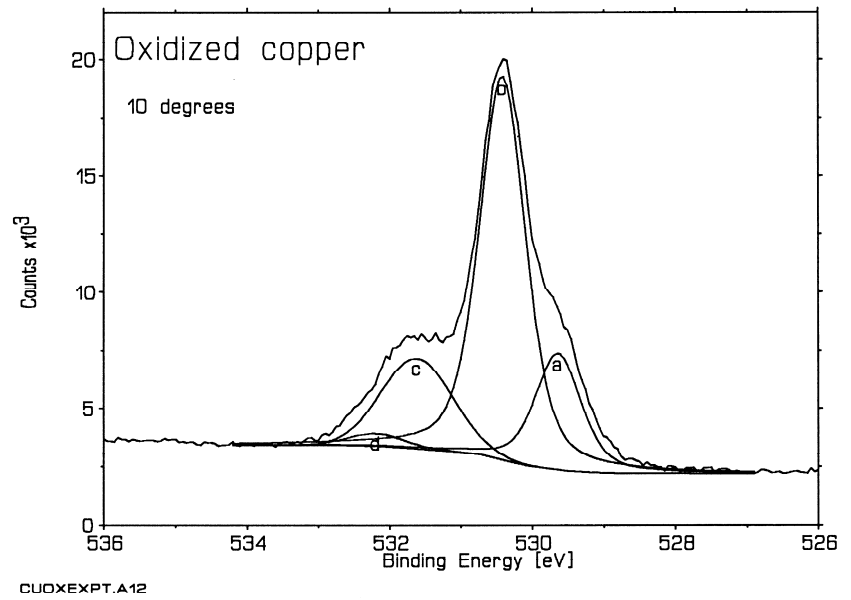
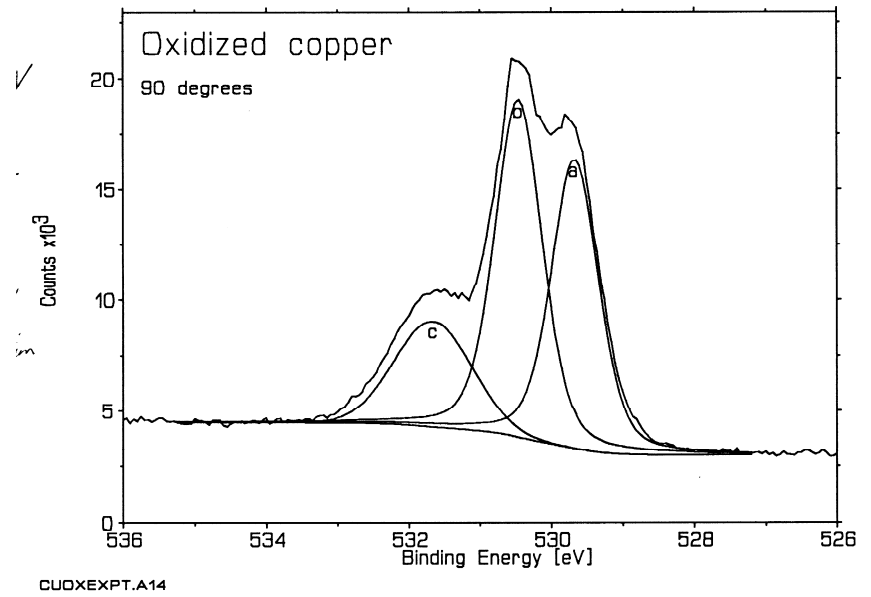
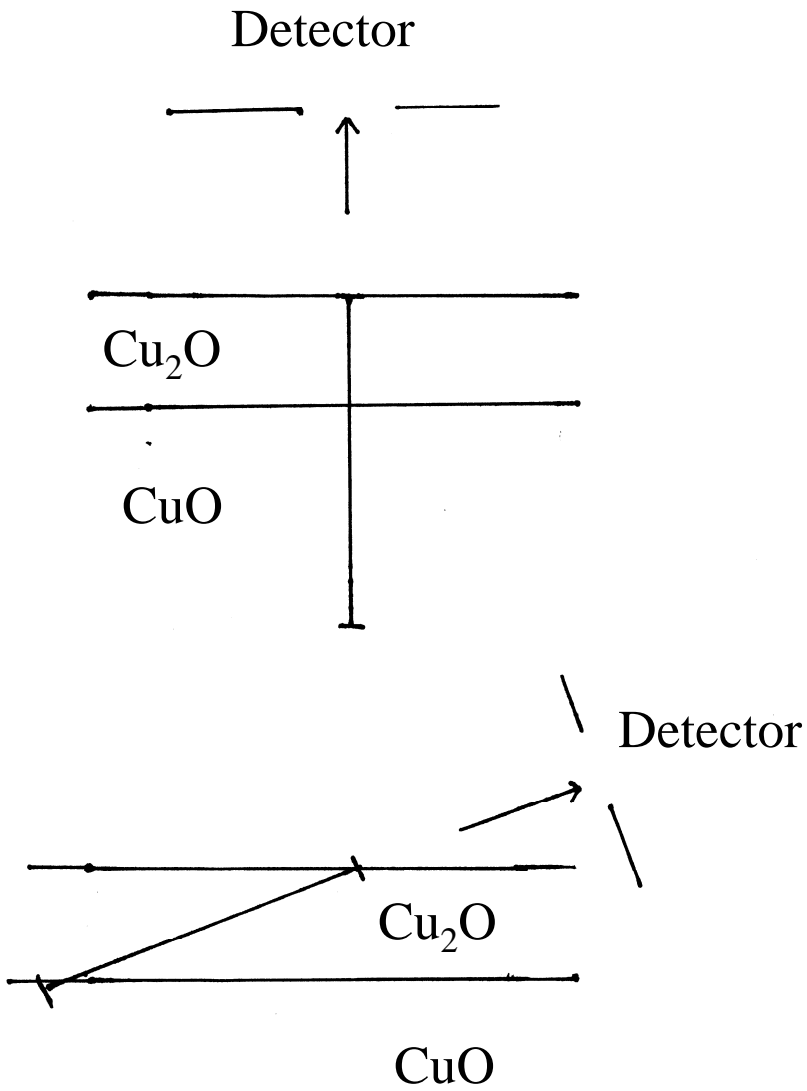
- Elemental identification
- Chemical state
- Quantitative surface composition
- In-Depth Composition (ARXPS, sputter depth profiles)
- Lateral distribution of surface elements and chemistry (XPS imaging)

Zr_{41.2}Ti_{13.8}Cu_{12.5}Ni₁₀Be_{22.5}



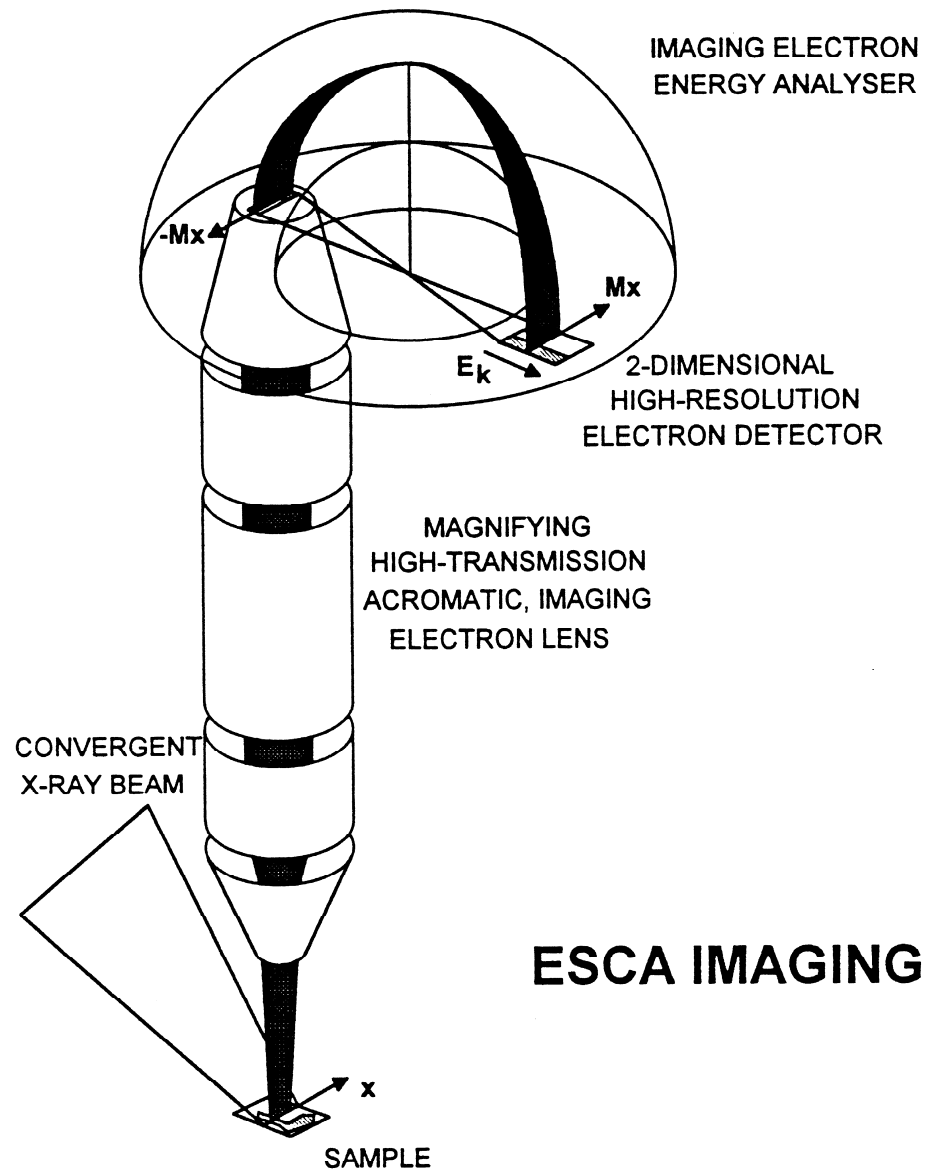
Thin oxide on Si





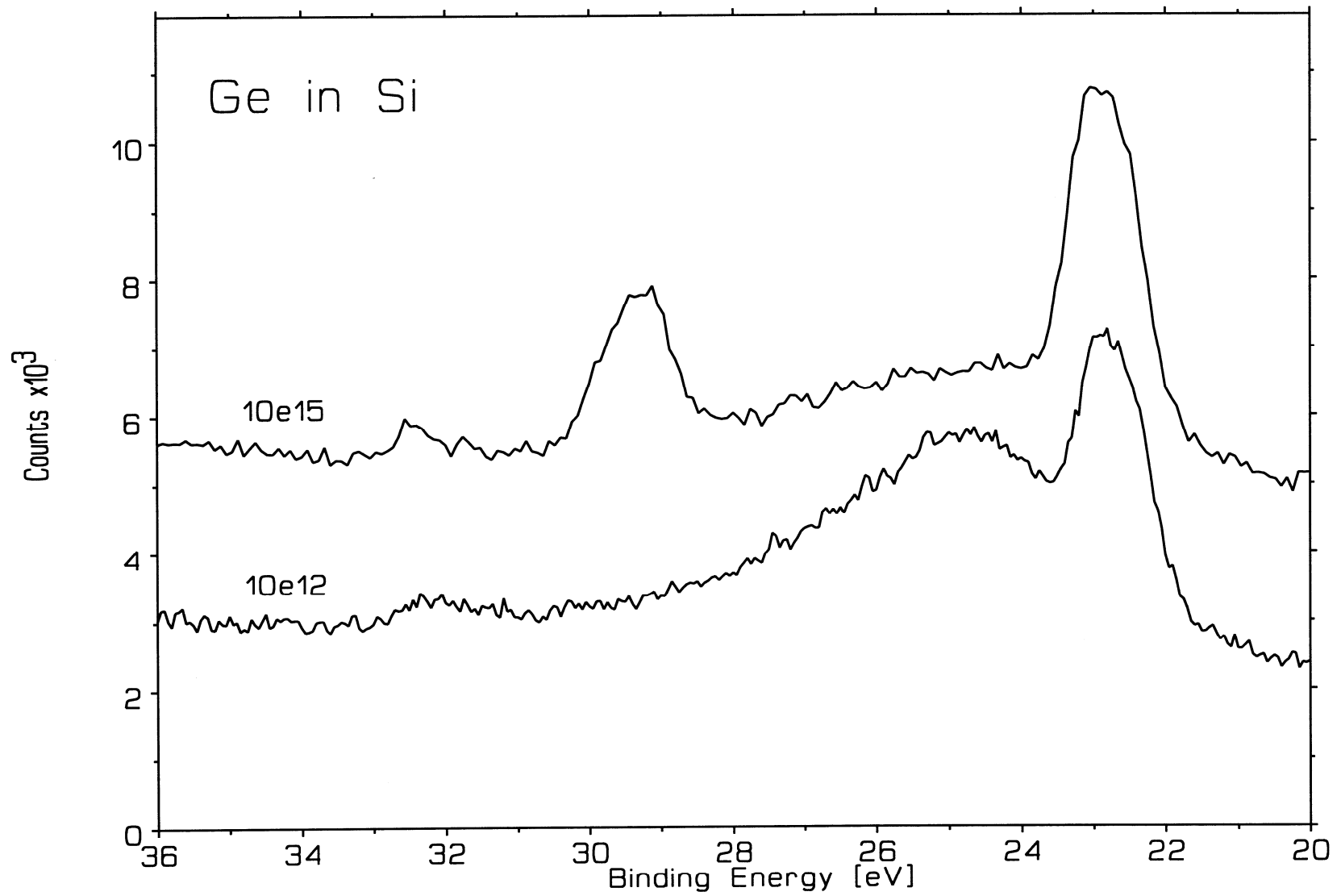
XPS imaging

Edge resolution of
3 microns or less
for the best instruments

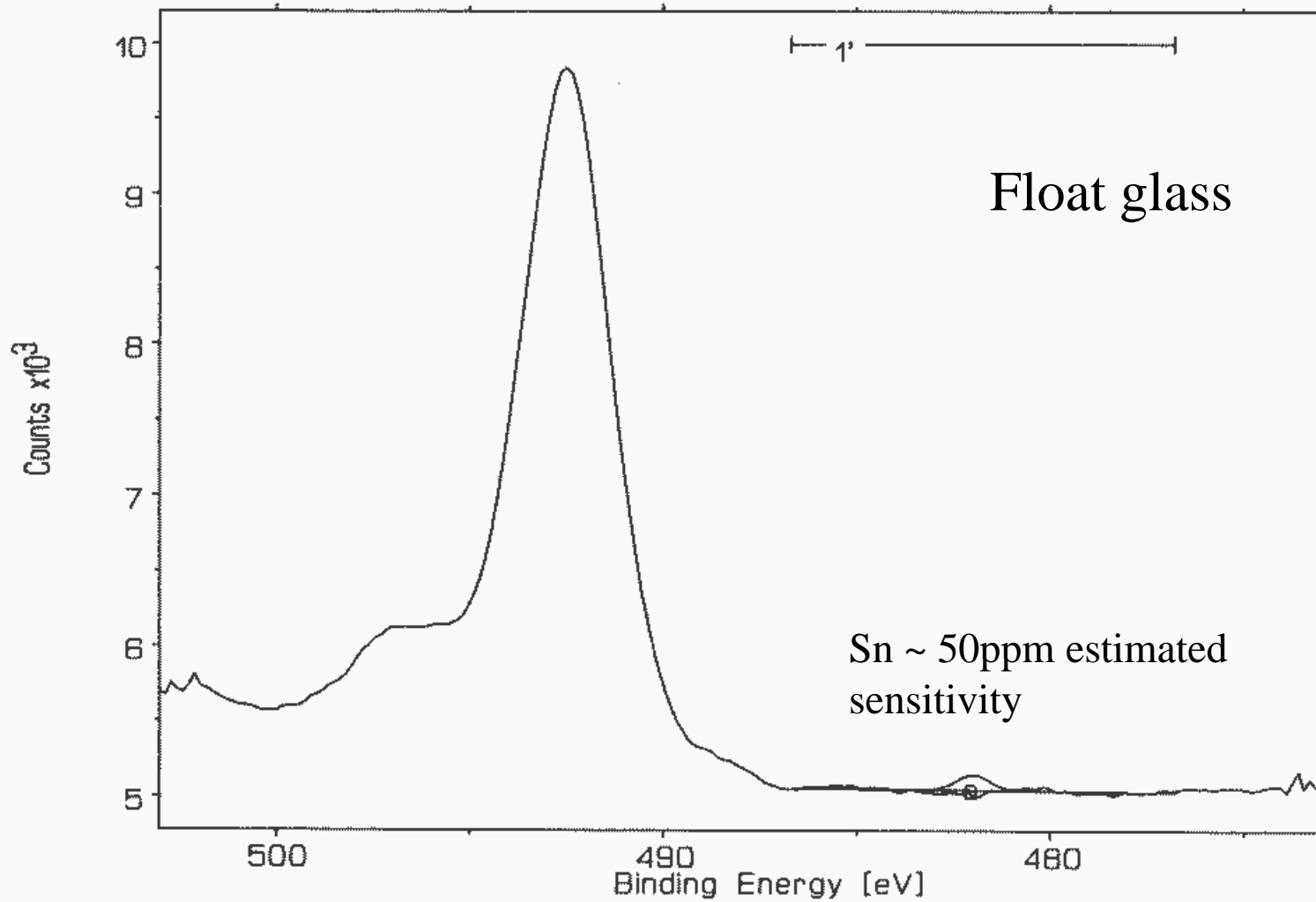


ESCA IMAGING

Detection Sensitivity- Ge implanted in Si

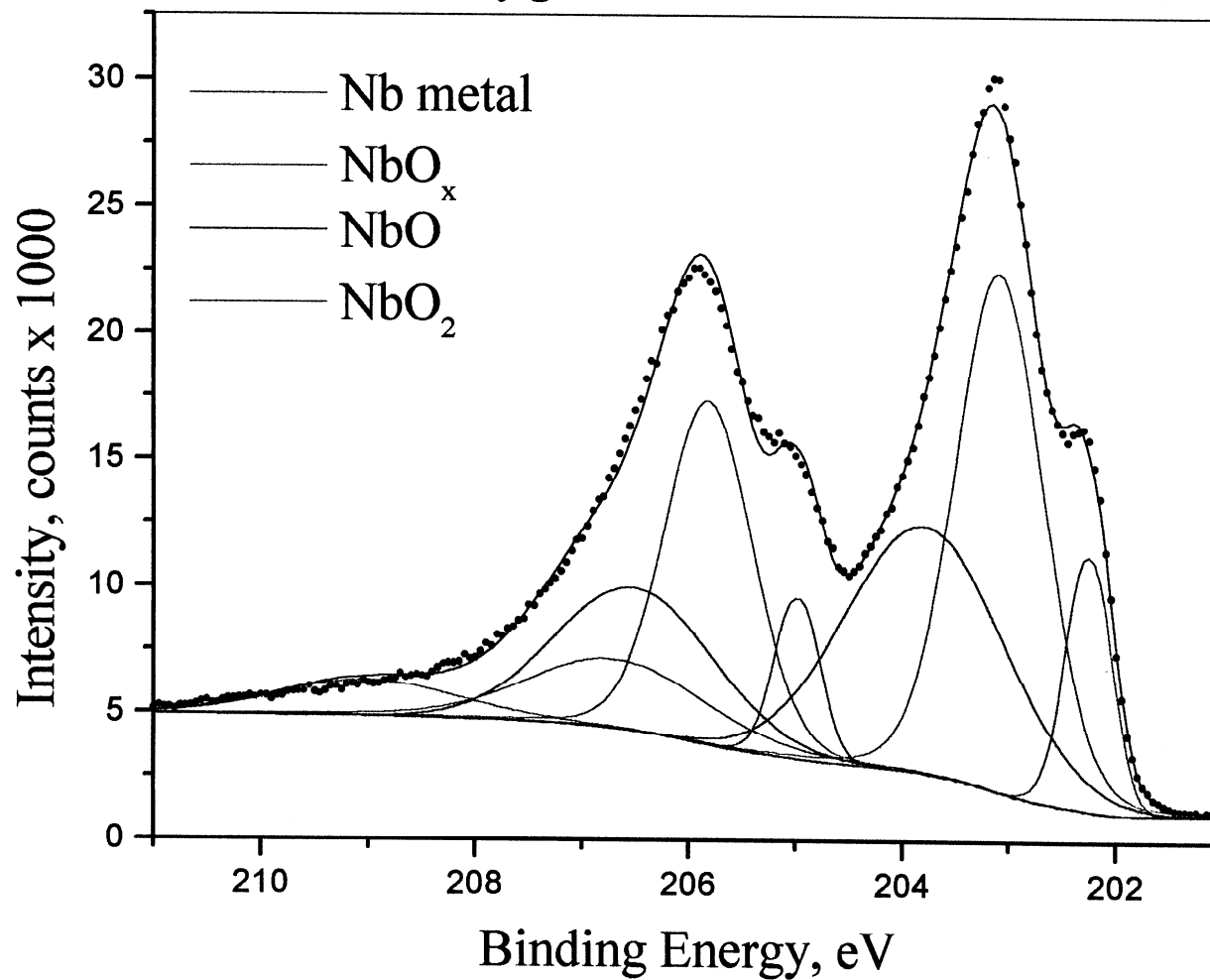


Detection Sensitivity

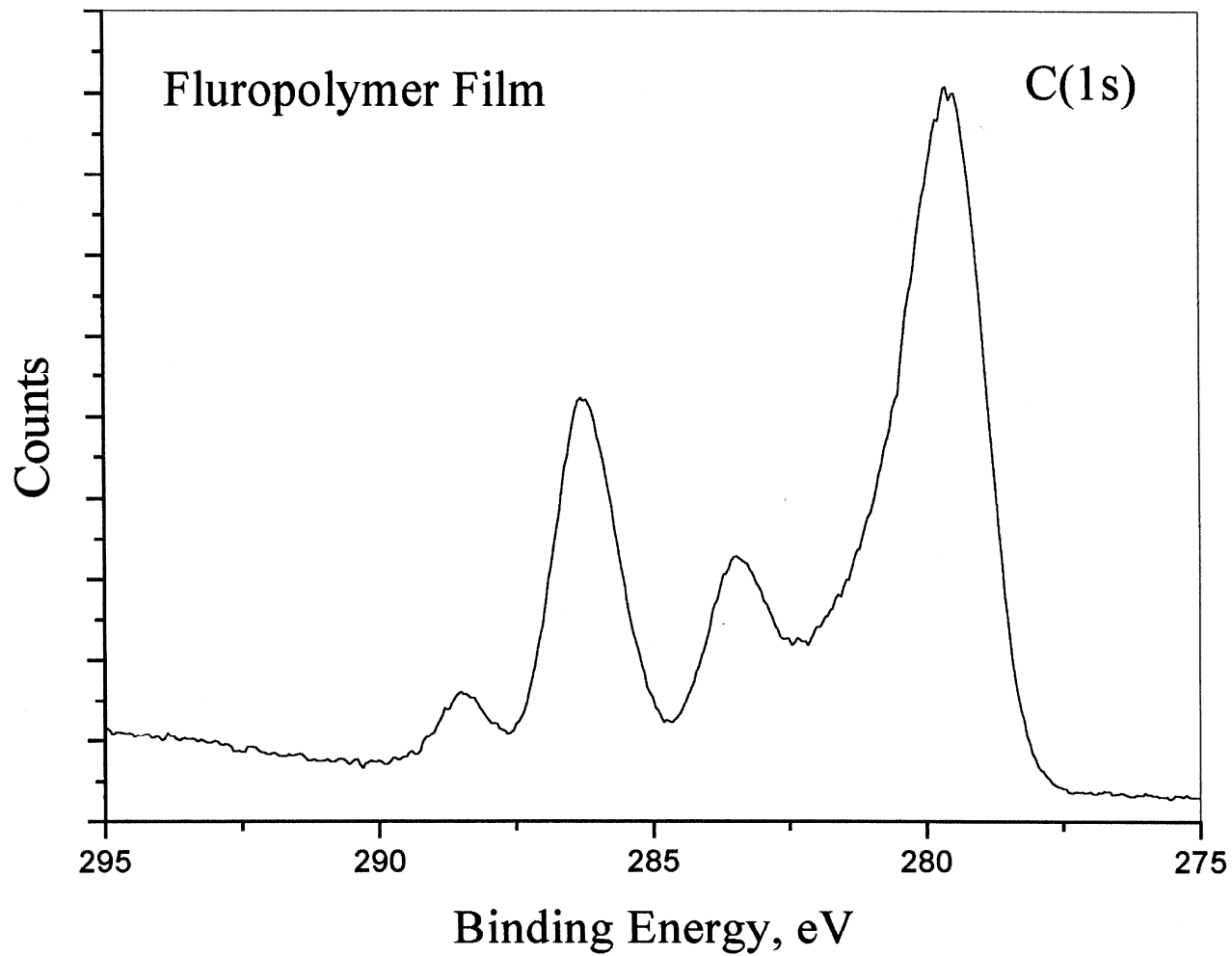


Metals

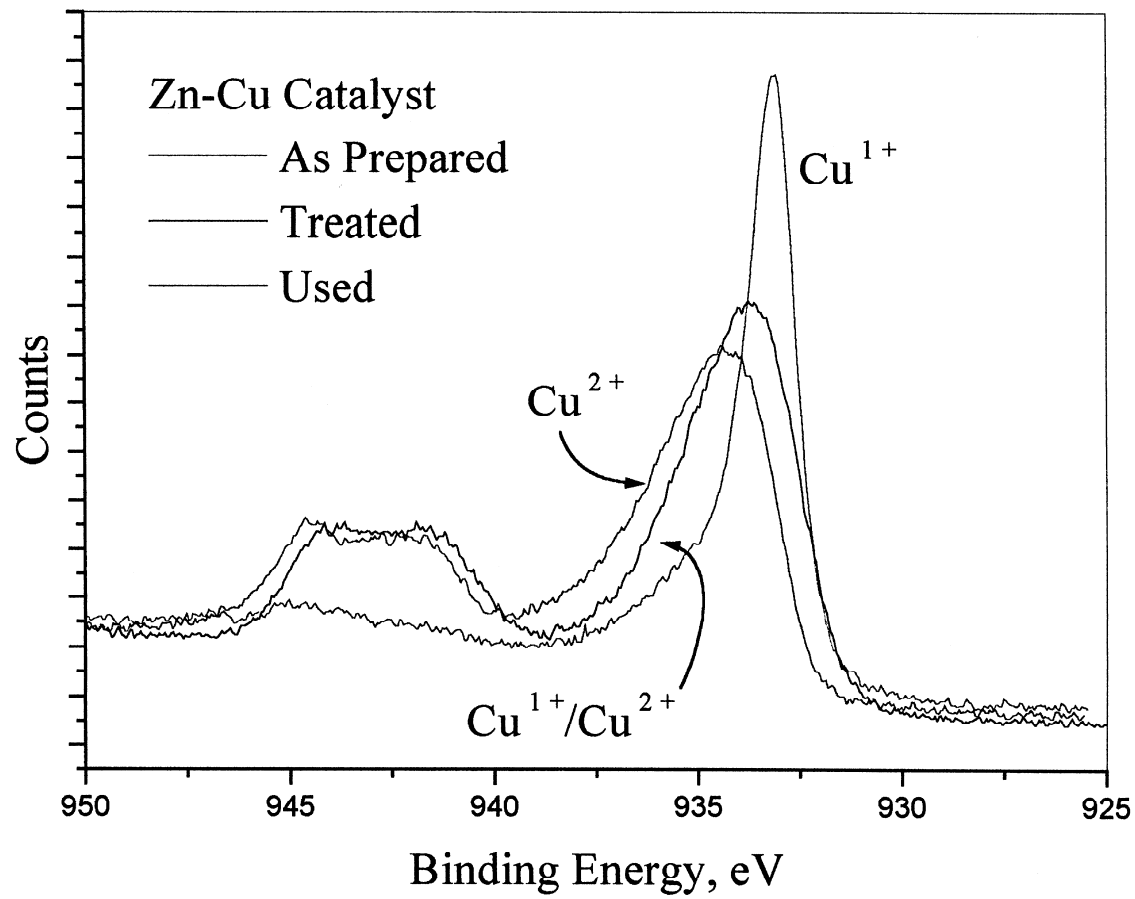
5×10^{-4} Pa oxygen at 973K for 45 minutes



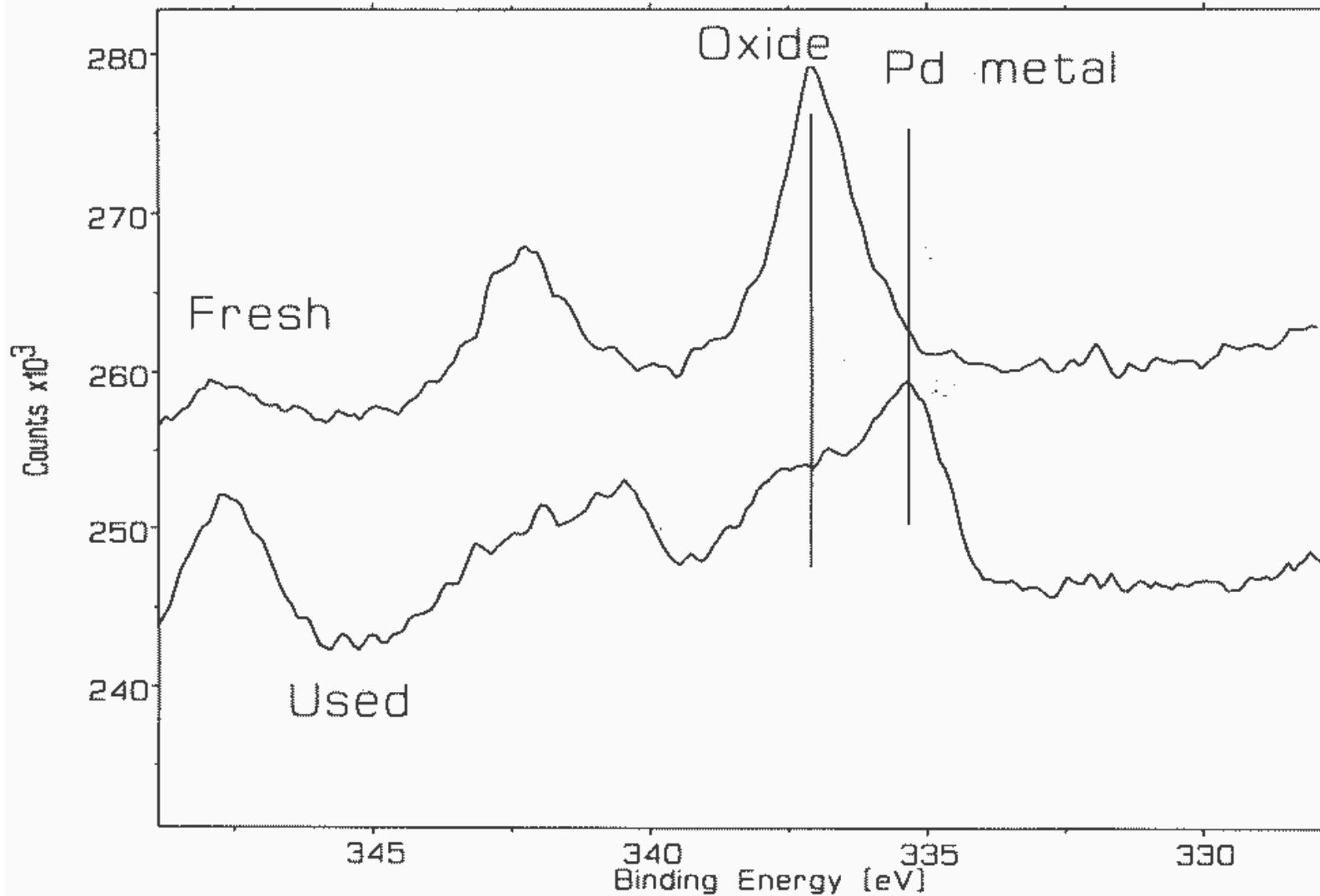
Polymers



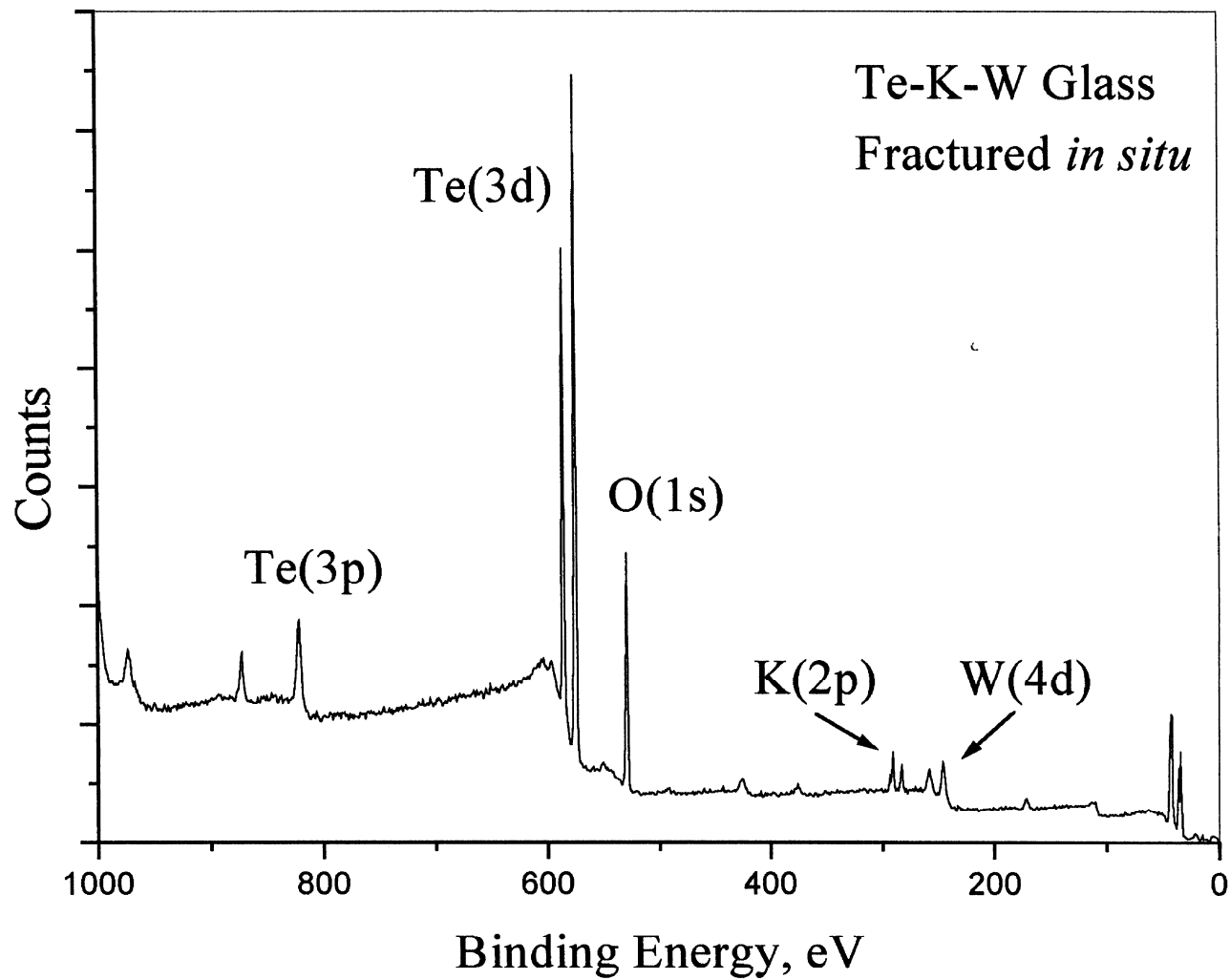
Catalysts



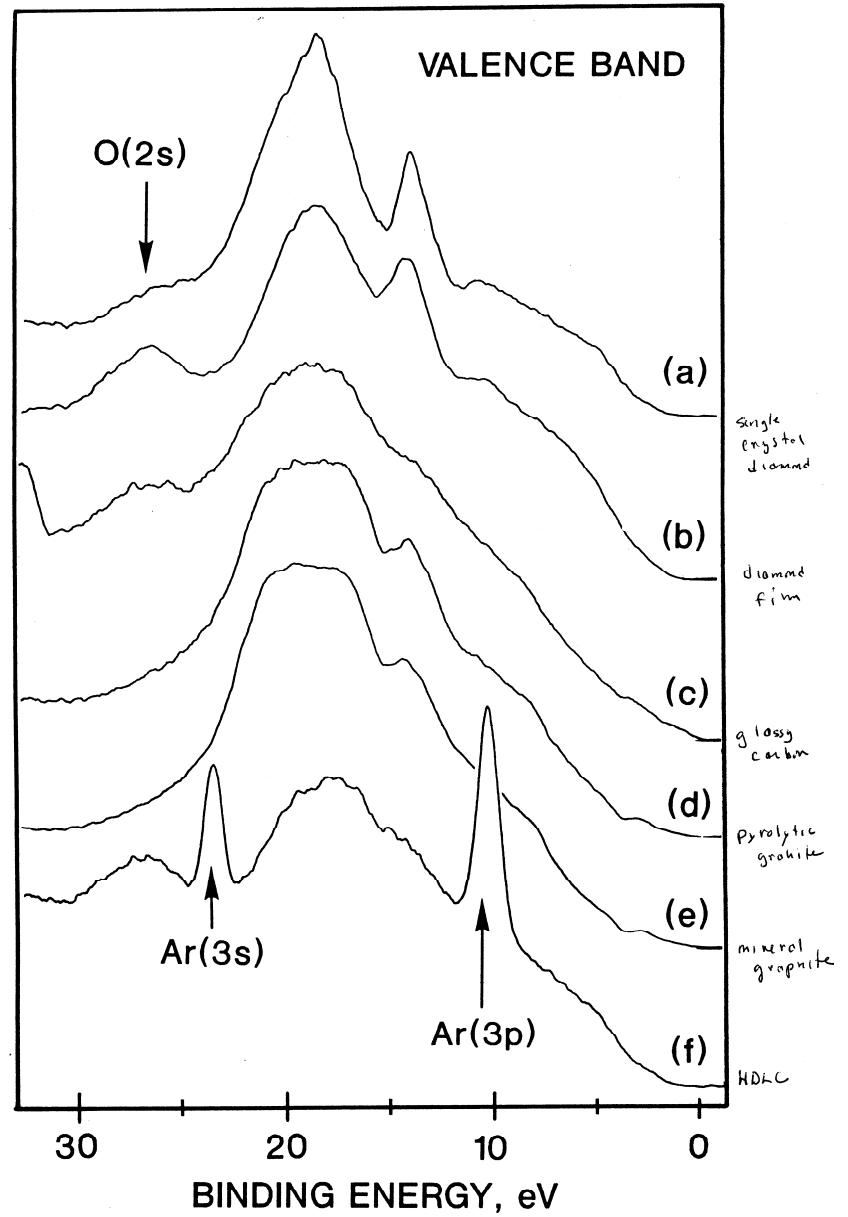
Pd loading of 0.05 wt.%



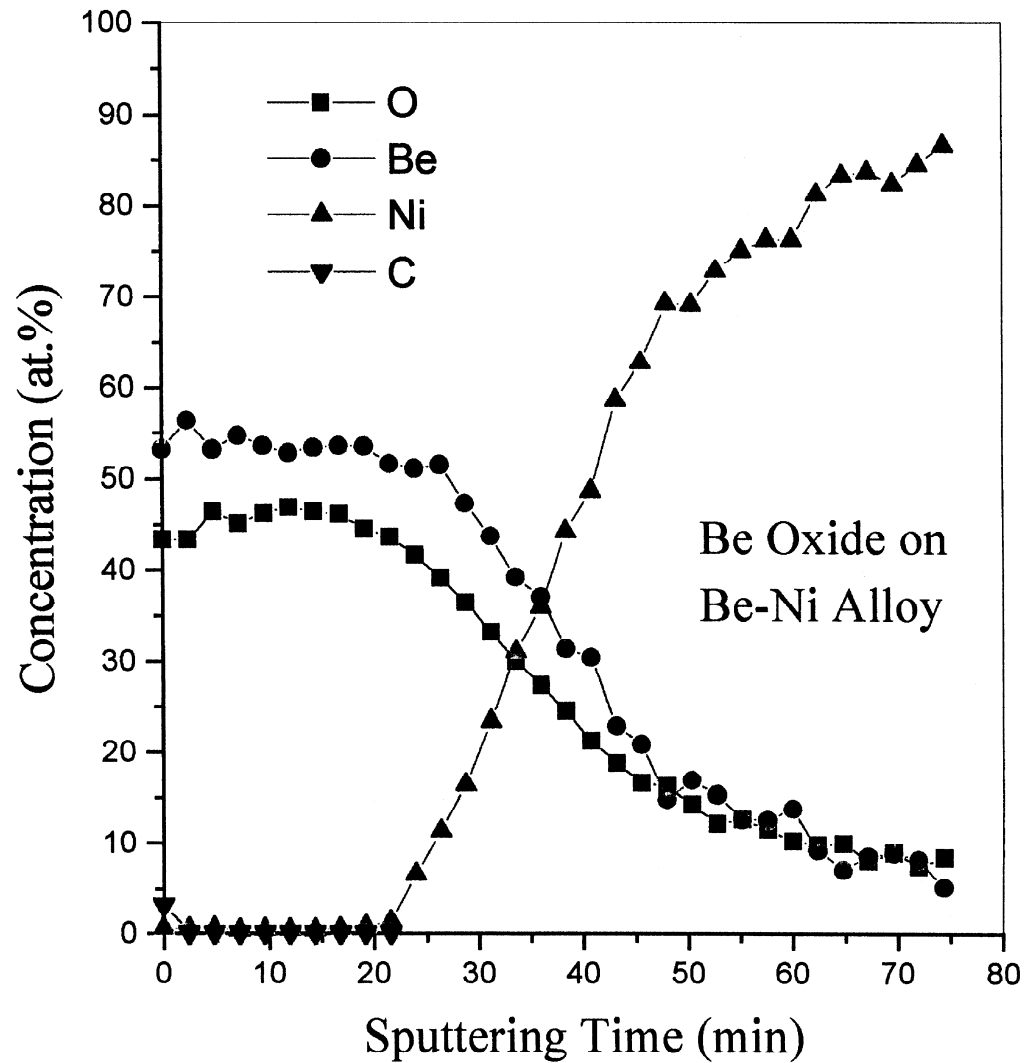
Insulators

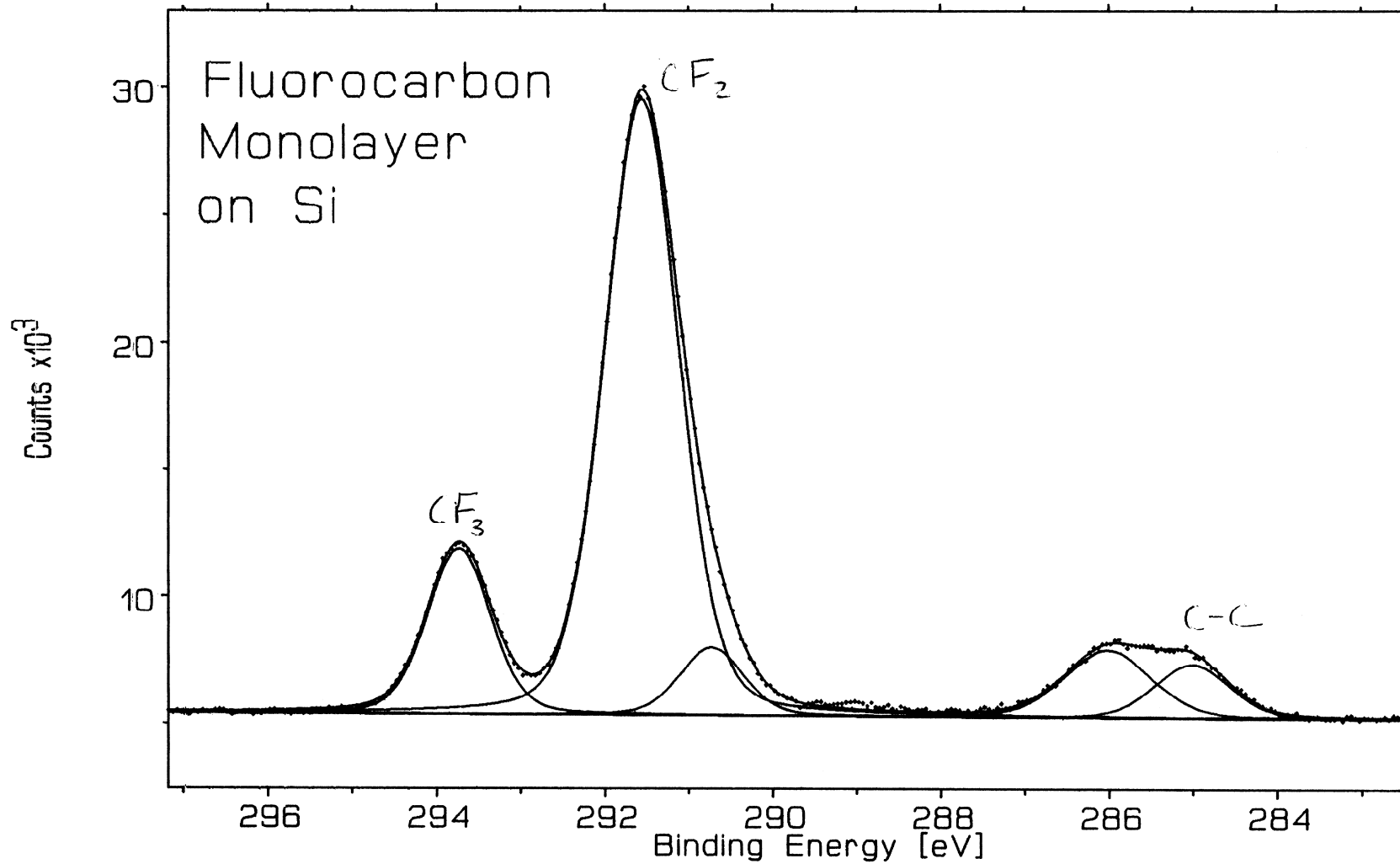


Valence Band

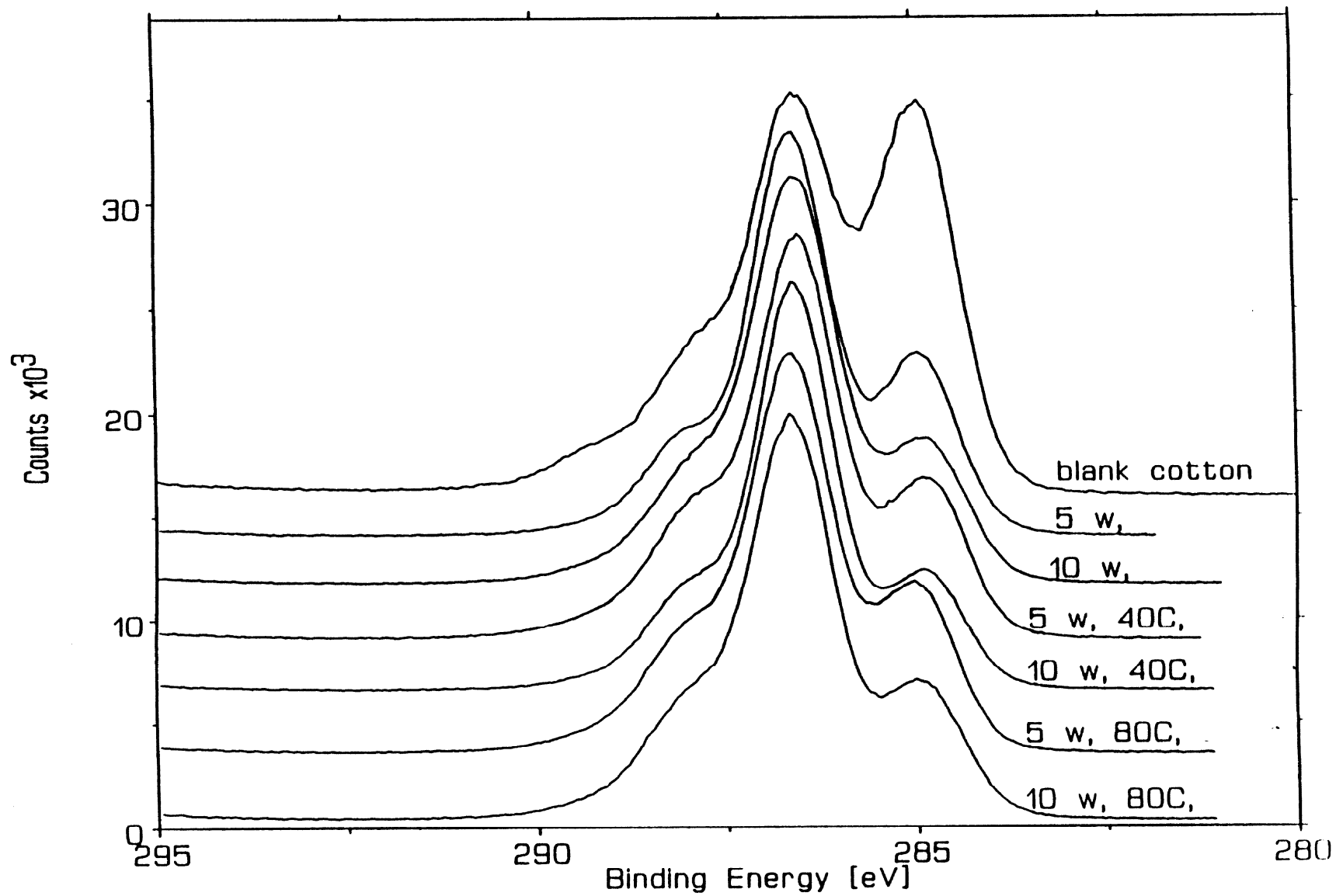


Depth Profiles





Effects of washing on cotton



Advantages

- Sensitive to 2-20 monolayers
- Can detect ca 10^{-3} atomic fraction
- Is especially useful for chemical shifts from the same element in different compounds
- Is the least destructive of the surface analysis techniques
- Has sensitivity range within a factor of 20
- Has minimal sample charging

Limitations

- Has moderate lateral resolution
- Is slower for sputter depth profiling than other methods

Lehigh Scienta ESCA300

Instrument features

- High power rotating anode x-ray source
- Multi-element monochromator
- High throughput analyzer and lens
- Channel plate detector
- Small spot and imaging capability
- Automated stage for multi-position analyses
- Charge compensation for insulators

Lehigh Scienta ESCA300

- In-situ heating and cooling
- Fracturing and scraping
- Argon ion etching
- Thin film deposition
- Gas exposures (low and high pressures)
- Residual gas analysis
- LEED available